

CMS Power-lines Protection Series (CMS-P)

Descriptions

The Ceramic Micro-Surge Protection Device (CMS) is manufactured from semiconducting ceramics which offer rugged protection and excellent transient energy absorption in a small SMD package. These devices are designed to suppress a variety of transient events, including those speified in IEC61000-4-2, IEC61000-4-5 and other standards used for Electromagnetic Compliance (EMC).

These devices are available in ceramic leadless chip form, eliminating lead inductance and assuring fast speed of response to transient surges. In addition, The CMS transient suppressors have temperature independent suppression characteristics, affording protection from -55 $^{\circ}$ C to 125 $^{\circ}$ C, which is much better than suppressors based on silicon semiconductor technology.

The CMS-P Series is specially designed for power-lines protection applications. It features a very high current protection capability with a very small size, also a very fast response thus a ultra low clamping voltage. These characteristics make CMS-P Series devices the best replacement of TVS and improvement of metal oxide (MOV) in high working voltage applications.

Features

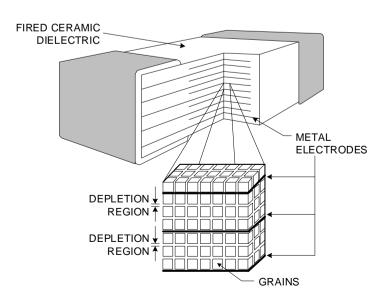
- Multi-Layers Construction Provides Higher Power Dissipation
- Surge Current Capability: 150A (@8/20µs)
- Better than UL94V-0 Flammability Rating
- No Temperature Derating up to 125°C Ambient
- Inherent Bi-directional Clamping
- Low Clamping Voltage
- "Zero" Lead Inductance
- RoHS compliant

Applications

- LED
- Surge protection for IEC/EN 61547
- Surge protection for IEC61000-4-5
- EFT protection for IEC 61000-4-4 (Level 4)
- ESD protection for IEC 61000-4-2 (Level 4)

Order Information

Device Size	Quantity	Reel Size	
0604	3000 pcs	7 Inch	
	3000 pcs	(178mm)	



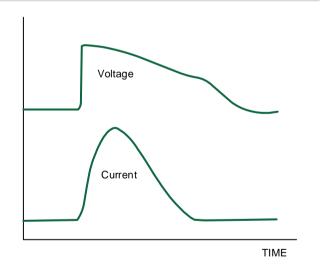
Multilayer Internal Construction



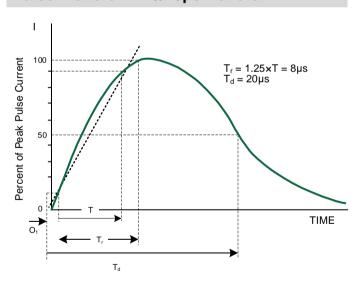
Device Ratings and Specifications

Parameter	Symbol	Condition	Value	Unit
Maximum Continuous a.c. Voltage	V _{M(AC)}	50~60Hz	46	V
Maximum Continuous d.c. Voltage	V _{M(DC)}		60	V
Nominal Varistor Voltage	V _N	@1mA	69~83	V
Maximum Leakage Current	lL	@V _M	30	μΑ
Maximum Clamping Voltage	Vc	@lc	130	V
Class Current	Ic	tp = 8/20µs	1	А
Peak Pulse Current 1 Time	I _{PP}	tp = 8/20µs	150	А
Rated Energy	Ε _T	10/1000µs	0.4	J
Operating Temperature Range			-55 to +125	°C
Storage Temperature			-55 to +150	°C

Surge Response - 8/20µs waveform

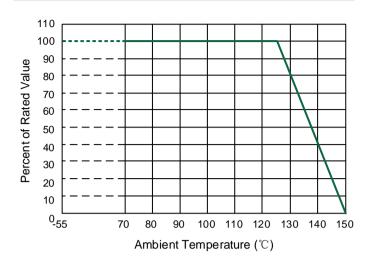


Pulse Waveform - 8/20µs waveform

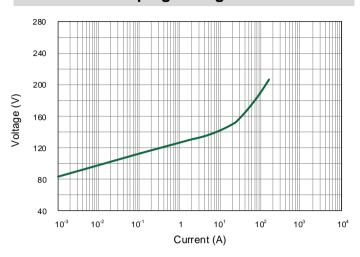




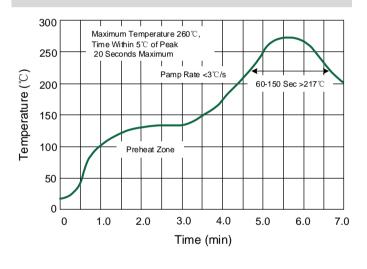
Current, Energy and Power Derating Curve



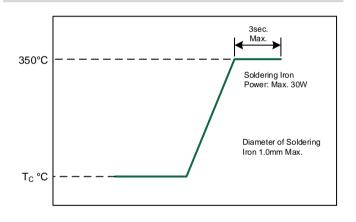
Maximum Clamping Voltage



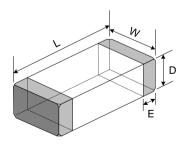
Lead-free Re-flow Solder Profile



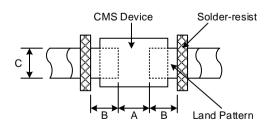
Iron Soldering Profile



Product Dimensions



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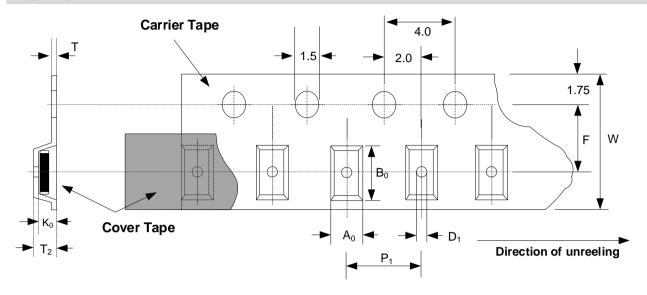


Recommended PCB Pattern

SIZE	L	w	D Max.	E	Α	В	С
0604	1.6 +0.30/-0.20	0.80 +0.40/-0.20	1.3	0.10~0.50	0.8~1.0	0.6~0.8	0.8~1.2

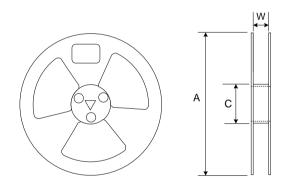


Tape Specifications



Туре	A ₀	B ₀	K ₀	P ₁	w	F
CMS0604	1.20 ±0.10	1.85 ±0.10	1.32Max	4.00 ±0.10	8.00 ±0.20	3.50±0.05

Reel Dimension



Tuno	Snoc	D	imensions(mm)
Туре	Spec.	Α	w	С
0604	7"*8mm	178	8.4+1.5/-0.0	58

Storage

- Operating and storage temperature range (individual chip without packing): -55 °C ~ +125 °C.
- Storage temperature range (packaging conditions): -10 °C ~+40 °C RH 70% (Max.).
- The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Package must be stored at 40 °C or less and 70 % RH or less.
- The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust of harmful gas (e.g. HCl, sulfurous gas of H₂S).
- Packaging material may be deformed if package are stored where they are exposed to heat of direct sunlight.
- Solderability shall be guaranteed for 12 months from the date of delivery on condition that they are stored at the environment specified in Clause 2. For those parts, which passed more than 12 months shall be checked solder-ability before use.



Environmental Reliability Test

Item	Requirment	Test Condition
High Temperature Storage	 Breakdown voltage change: within ±10% No mechanical damage 	 Temperature: 150 ± 2°C Time: 1000 (+24) hours Test after placing in ambient temperature for 1~2hours
Low Temperature Storage	Breakdown voltage change: within ±10% No mechanical damage	 Temperature: -55± 2°C Time: 1000 (+24) hours Test after placing in ambient temperature for 1~2hours
Thermal Shock	 Breakdown voltage change: within ±10% No mechanical damage 	 Temperature, Time:-55 (±2) °C/30min~ 125 (±2) °C/30min Transforming interval: 2~3min. Tested cycle: 100 cycles. Test after placing in ambient temperature for 1~2hours
High Temperature Load	 Breakdown voltage change: within ±10% No mechanical damage 	 Temperature: 125 ± 2°C Rated working voltage applied Time: 1000 (+24) hours Test after placing in ambient temperature for 1~2hours
Damp Heat Load / Humidity Load	 Breakdown voltage change: within ±10% No mechanical damage 	 Temperature: 85±2°C Humidity: 85%±2RH Rated working voltage applied Time: 500 (+24) hours Test after placing in ambient temperature for 1~2hours

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Specifications are subject to change without notice.

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